Infineon Technologies - MB96F625ABPMC1-GSE2 Datasheet

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

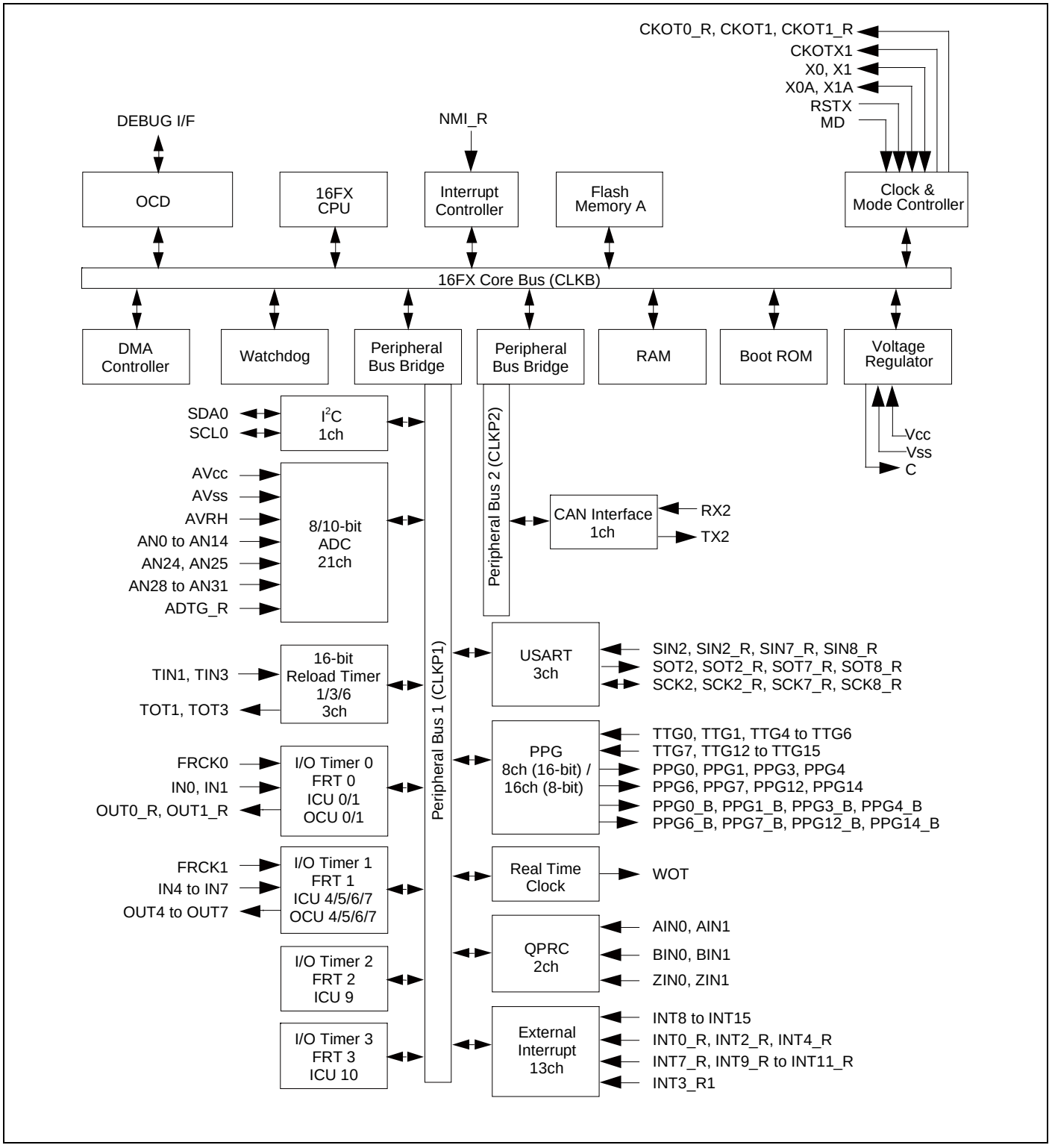
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16FX
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SCI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	160KB (160K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 21x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb96f625abpmc1-gse2

Contents

2. Block Diagram

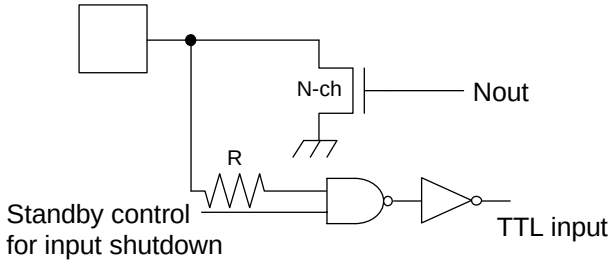


5. Pin Circuit Type

Pin no.	I/O circuit type*	Pin name
1	Supply	AVss
2	G	AVRH
3	K	P06_2 / AN2
4	K	P06_3 / AN3 / PPG3
5	K	P06_4 / AN4 / PPG4
6	K	P06_5 / AN5
7	K	P06_6 / AN6 / PPG6
8	K	P06_7 / AN7 / PPG7
9	I	P05_0 / AN8 / SIN2 / INT3_R1
10	K	P05_1 / AN9 / SOT2
11	I	P05_2 / AN10 / SCK2
12	K	P05_3 / AN11 / TIN3 / WOT
13	K	P05_4 / AN12 / TOT3 / INT2_R
14	K	P05_5 / AN13 / INT0_R / NMI_R
15	K	P05_6 / AN14 / INT4_R
16	H	P04_2 / IN6 / INT9_R / TTG6 / TTG14
17	H	P04_3 / IN7 / TTG7 / TTG15
18	Supply	Vss
19	B	P04_0 / X0A
20	B	P04_1 / X1A
21	C	MD
22	H	P17_0
23	O	DEBUG I/F
24	M	P00_0 / INT8 / SCK7_R / PPG0_B
25	H	P00_1 / INT9 / SOT7_R / PPG1_B
26	M	P00_2 / INT10 / SIN7_R
27	M	P00_3 / INT11 / SCK8_R / PPG3_B
28	H	P00_4 / INT12 / SOT8_R / PPG12_B
29	M	P00_5 / INT13 / SIN8_R / PPG14_B
30	H	P00_6 / INT14
31	H	P00_7 / INT15
32	H	P01_0 / TIN1 / CKOT1 / OUT0_R

Pin no.	I/O circuit type*	Pin name
33	N	P04_5 / SCL0
34	O	DEBUG I/F
35	H	P17_0
36	C	MD
37	A	X0
38	A	X1
39	Supply	Vss
40	B	P04_0 / X0A
41	B	P04_1 / X1A
42	C	RSTX
43	J	P11_7 / SEG3 / IN0_R
44	J	P11_0 / COM0
45	J	P11_1 / COM1 / PPG0_R
46	J	P11_2 / COM2 / PPG1_R
47	J	P11_3 / COM3 / PPG2_R
48	J	P12_0 / SEG4 / IN1_R
49	J	P12_1 / SEG5 / TIN1_R / PPG0_B
50	J	P12_2 / SEG6 / TOT1_R / PPG1_B
51	J	P12_4 / SEG8
52	J	P12_5 / SEG9 / TIN2_R / PPG2_B
53	J	P12_6 / SEG10 / TOT2_R / PPG3_B
54	J	P12_7 / SEG11 / INT1_R
55	J	P01_1 / SEG21 / CKOT1
56	J	P01_3 / SEG23
57	L	P03_0 / SEG36 / V0
58	L	P03_1 / SEG37 / V1
59	L	P03_2 / SEG38 / V2
60	L	P03_3 / SEG39 / V3
61	M	P03_4 / RX0 / INT4
62	H	P03_5 / TX0
63	H	P03_6 / INT0 / NMI
64	Supply	Vcc

*: See “I/O Circuit Type” for details on the I/O circuit types.

Type	Circuit	Remarks
O		• Open-drain I/O • Output 25mA, Vcc = 2.7V • TTL input

■Precautions Related to Usage of Devices
Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

12.2 Precautions for Package Mounting
Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

■Lead Insertion Type
Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

■Surface Mount Type
Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

■Lead-Free Packaging
CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

■Storage of Semiconductor Devices
Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

1. Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
2. Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
   When you open Dry Package that recommends humidity 40% to 70% relative humidity.
3. When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
4. Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

■Baking
Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

13. Handling Devices

Special care is required for the following when handling the device:

- Latch-up prevention
- Unused pins handling
- External clock usage
- Notes on PLL clock mode operation
- Power supply pins (V_{cc}/V^{ss})
- Crystal oscillator and ceramic resonator circuit
- Turn on sequence of power supply to A/D converter and analog inputs
- Pin handling when not using the A/D converter
- Notes on Power-on
- Stabilization of power supply voltage
- Serial communication
- Mode Pin (MD)

13.1 Latch-up prevention

CMOS IC chips may suffer latch-up under the following conditions:

- A voltage higher than V_{CC} or lower than V_{SS} is applied to an input or output pin.
- A voltage higher than the rated voltage is applied between V_{cc} pins and V_{ss} pins.
- The AV_{CC} power supply is applied before the V_{CC} voltage.

Latch-up may increase the power supply current dramatically, causing thermal damages to the device.

For the same reason, extra care is required to not let the analog power-supply voltage (AV_{CC}, AVRH) exceed the digital power-supply voltage.

13.2 Unused pins handling

Unused input pins can be left open when the input is disabled (corresponding bit of Port Input Enable register PIER = 0).

Leaving unused input pins open when the input is enabled may result in misbehavior and possible permanent damage of the device. To prevent latch-up, they must therefore be pulled up or pulled down through resistors which should be more than 2kΩ.

Unused bidirectional pins can be set either to the output state and be then left open, or to the input state with either input disabled or external pull-up/pull-down resistor as described above.

14. Electrical Characteristics

14.1 Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating		Unit	Remarks
			Min	Max		
Power supply voltage*1	V_{CC}	-	V_{SS} - 0.3	V_{SS} + 6.0	V	
Analog power supply voltage*1	AV_{CC}	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$V_{CC} = AV_{CC}$*2
Analog reference voltage*1	AVRH	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$AV_{CC} \geq AVRH$, $AVRH \geq AV_{SS}$
Input voltage*1	V_I	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$V_I \leq V_{CC}$ + 0.3V*3
Output voltage*1	V_O	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$V_O \leq V_{CC}$ + 0.3V*3
Maximum Clamp Current	I_{CLAMP}	-	-4.0	+4.0	mA	Applicable to general purpose I/O pins *4
Total Maximum Clamp Current	$\Sigma\lvert I_{CLAMP}\rvert$	-	-	17	mA	Applicable to general purpose I/O pins *4
"L" level maximum output current	I_{OL}	-	-	15	mA	
"L" level average output current	I_{OLAV}	-	-	4	mA	
"L" level maximum overall output current	ΣI_{OL}	-	-	42	mA	
"L" level average overall output current	ΣI_{OLAV}	-	-	21	mA	
"H" level maximum output current	I_{OH}	-	-	-15	mA	
"H" level average output current	I_{OHAV}	-	-	-4	mA	
"H" level maximum overall output current	ΣI_{OH}	-	-	-42	mA	
"H" level average overall output current	ΣI_{OHAV}	-	-	-21	mA	
Power consumption*5	P_D	T_A= +125°C	-	352*6	mW	
Operating ambient temperature	T_A	-	-40	+125*7	°C	
Storage temperature	T_{STG}	-	-55	+150	°C	

*1: This parameter is based on $V_{SS} = AV_{SS} = 0V$.

*2: AV_{CC} and V_{CC} must be set to the same voltage. It is required that AV_{CC} does not exceed V_{CC} and that the voltage at the analog inputs does not exceed AV_{CC} when the power is switched on.

*3: V_I and V_O should not exceed V_{CC} + 0.3V. V_I should also not exceed the specified ratings. However if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating. Input/Output voltages of standard ports depend on V_{CC}.

*4: Applicable to all general purpose I/O pins (Pnn_m).

- Use within recommended operating conditions.
- Use at DC voltage (current).
- The +B signal should always be applied a limiting resistance placed between the +B signal and the microcontroller.
- The value of the limiting resistance should be set so that when the +B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
- Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the V_{CC} pin, and this may affect other devices.
- Note that if a +B signal is input when the microcontroller power supply is off (not fixed at 0V), the power supply is provided from the pins, so that incomplete operation may result.
- Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the Power reset.

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current in Timer modes[*2]	I_{CCTPLL}	Vcc	PLL Timer mode with CLKPLL = 32MHz (CLKRC and CLKSC stopped)	-	1800	2245	µA	T_A = +25°C
				-	-	3165	µA	T_A = +105°C
				-	-	3975	µA	T_A = +125°C
	$I_{CCTMAIN}$		Main Timer mode with CLKMC = 4MHz, SMCR:LPMSS = 0 (CLKPLL, CLKRC and CLKSC stopped)	-	285	325	µA	T_A = +25°C
				-	-	1085	µA	T_A = +105°C
				-	-	1930	µA	T_A = +125°C
	I_{CCTRCH}		RC Timer mode with CLKRC = 2MHz, SMCR:LPMSS = 0 (CLKPLL, CLKMC and CLKSC stopped)	-	160	210	µA	T_A = +25°C
				-	-	1025	µA	T_A = +105°C
				-	-	1840	µA	T_A = +125°C
	I_{CCTRCL}		RC Timer mode with CLKRC = 100kHz (CLKPLL, CLKMC and CLKSC stopped)	-	35	75	µA	T_A = +25°C
				-	-	855	µA	T_A = +105°C
				-	-	1640	µA	T_A = +125°C
	I_{CCTSUB}		Sub Timer mode with CLKSC = 32kHz (CLKMC, CLKPLL and CLKRC stopped)	-	25	65	µA	T_A = +25°C
				-	-	830	µA	T_A = +105°C
				-	-	1620	µA	T_A = +125°C

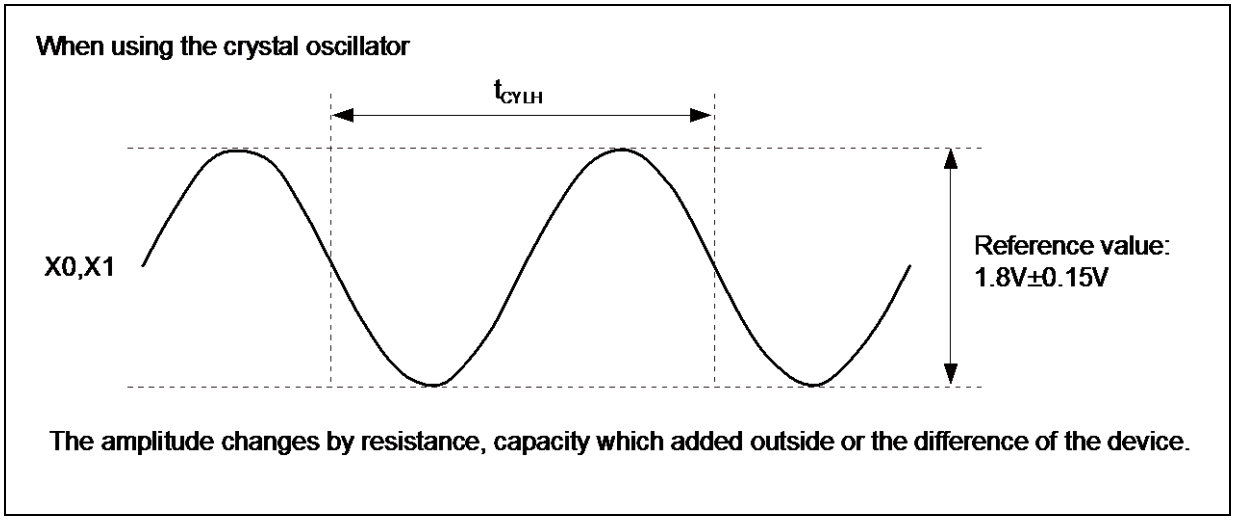
Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
"H" level output voltage	V_{OH4}	4mA type	$4.5V \le V_{CC} \le 5.5V$ $I_{OH} = -4mA$	V_{CC} - 0.5	-	V_{CC}	V	
			$2.7V \le V_{CC} < 4.5V$ $I_{OH} = -1.5mA$					
	V_{OH3}	3mA type	$4.5V \le V_{CC} \le 5.5V$ $I_{OH} = -3mA$	V_{CC} - 0.5	-	V_{CC}	V	
			$2.7V \le V_{CC} < 4.5V$ $I_{OH} = -1.5mA$					
"L" level output voltage	V_{OL4}	4mA type	$4.5V \le V_{CC} \le 5.5V$ $I_{OL} = +4mA$	-	-	0.4	V	
			$2.7V \le V_{CC} < 4.5V$ $I_{OL} = +1.7mA$					
	V_{OL3}	3mA type	$2.7V \le V_{CC} < 5.5V$ $I_{OL} = +3mA$	-	-	0.4	V	
	V_{OLD}	DEBUG I/F	$V_{CC} = 2.7V$ $I_{OL} = +25mA$	0	-	0.25	V	
Input leak current	I_{IL}	Pnn_m	$V_{SS} < V_I < V_{CC}$ $AV_{SS} < V_I <$ AV_{CC}, AVRH	- 1	-	+ 1	µA	
Pull-up resistance value	R_{PU}	Pnn_m	$V_{CC} = 5.0V \pm 10\%$	25	50	100	kΩ	
Input capacitance	C_{IN}	Other than C, Vcc, Vss, AVcc, AVss, AVRH	-	-	5	15	pF	

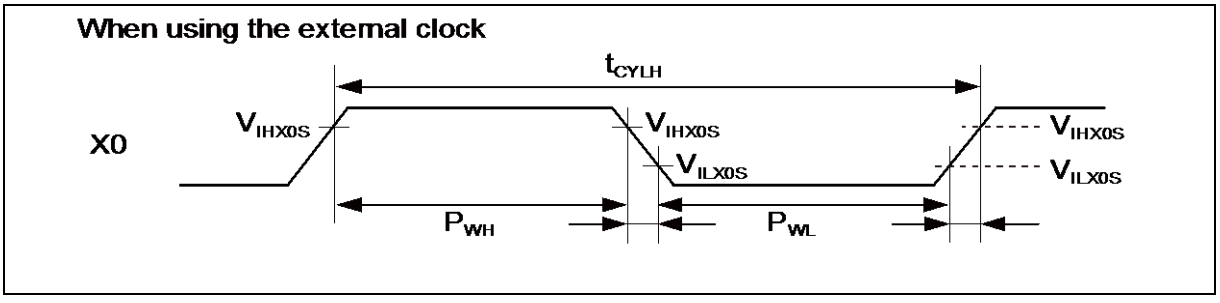
14.4 AC Characteristics

14.4.1 Main Clock Input Characteristics

(V_{CC} = AV_{CC} = 2.7V to 5.5V, VD=1.8V±0.15V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Input frequency	f_C	X0, X1	4	-	8	MHz	When using a crystal oscillator, PLL off
			-	-	8	MHz	When using an opposite phase external clock, PLL off
			4	-	8	MHz	When using a crystal oscillator or opposite phase external clock, PLL on
Input frequency	f_{FCI}	X0	-	-	8	MHz	When using a single phase external clock in “Fast Clock Input mode”, PLL off
			4	-	8	MHz	When using a single phase external clock in “Fast Clock Input mode”, PLL on
Input clock cycle	t_{CYLH}	-	125	-	-	ns	
Input clock pulse width	P_{WH}, P_{WL}	-	55	-	-	ns	

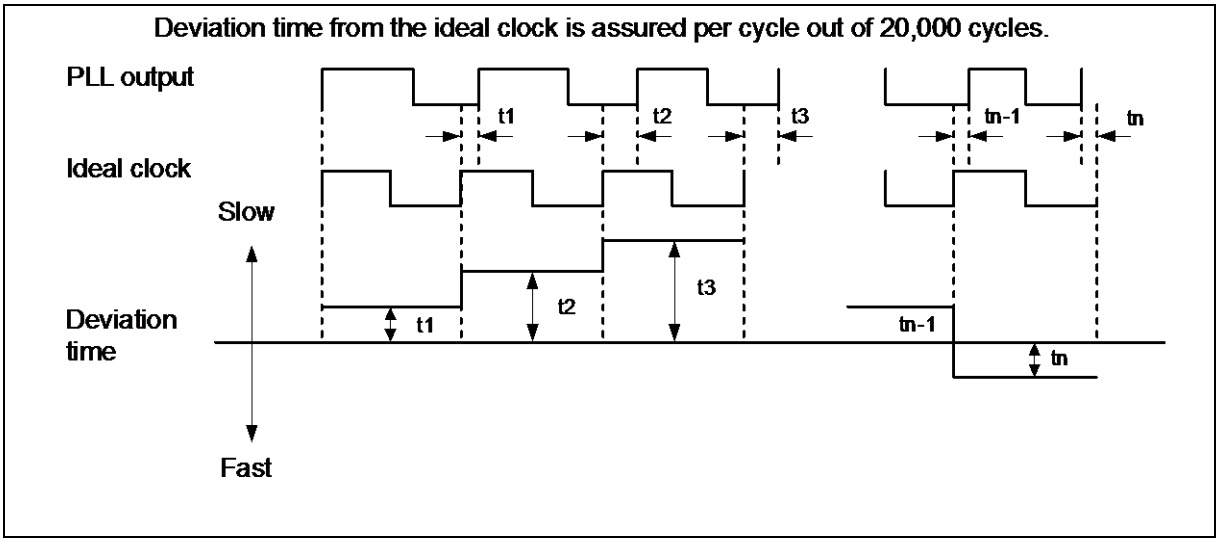




14.4.5 Operating Conditions of PLL

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

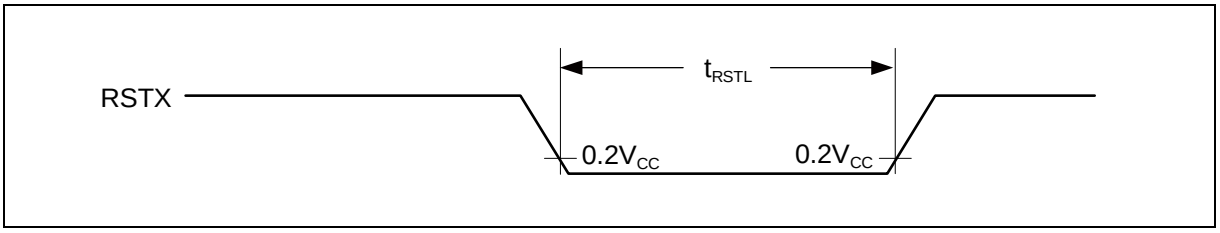
Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
PLL oscillation stabilization wait time	t_{LOCK}	1	-	4	ms	For CLKMC = 4MHz
PLL input clock frequency	f_{PLLI}	4	-	8	MHz	
PLL oscillation clock frequency	f_{CLKVCO}	56	-	108	MHz	Permitted VCO output frequency of PLL (CLKVCO)
PLL phase jitter	t_{PSKEW}	-5	-	+5	ns	For CLKMC (PLL input clock) ≥ 4MHz



14.4.6 Reset Input

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

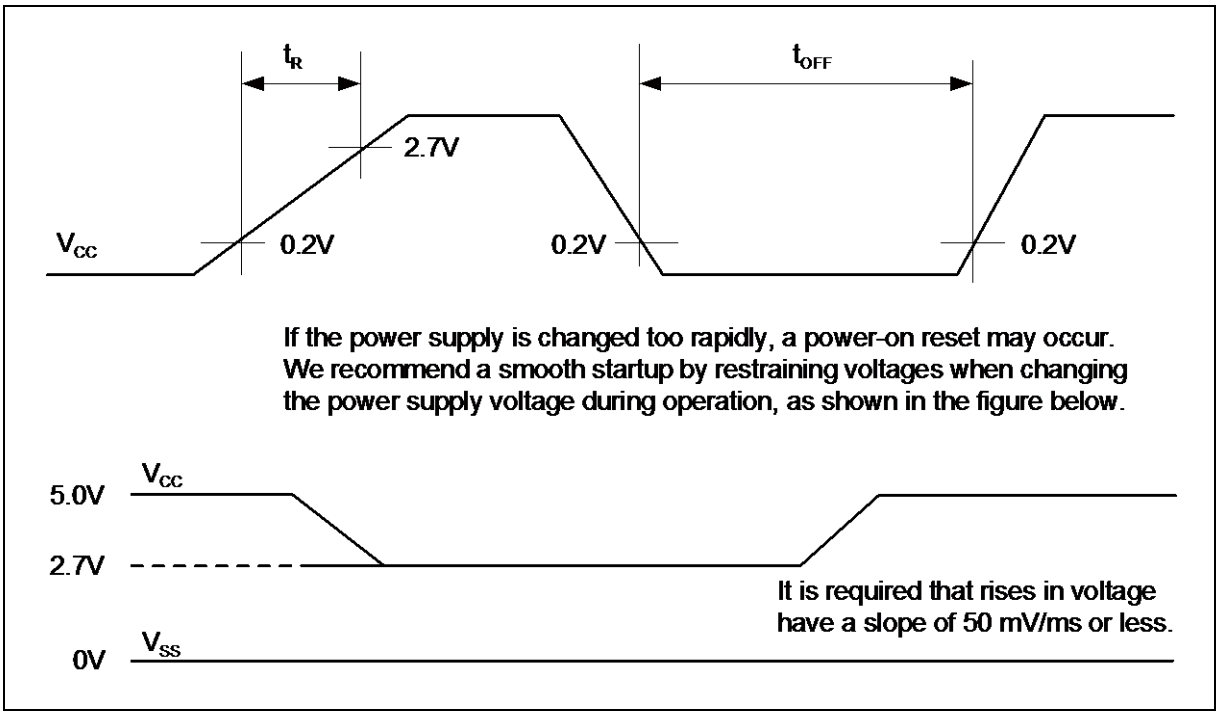
Parameter	Symbol	Pin name	Value		Unit
			Min	Max	
Reset input time	t_{RSTL}	RSTX	10	-	µs
Rejection of reset input time			1	-	µs



14.4.7 Power-on Reset Timing

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

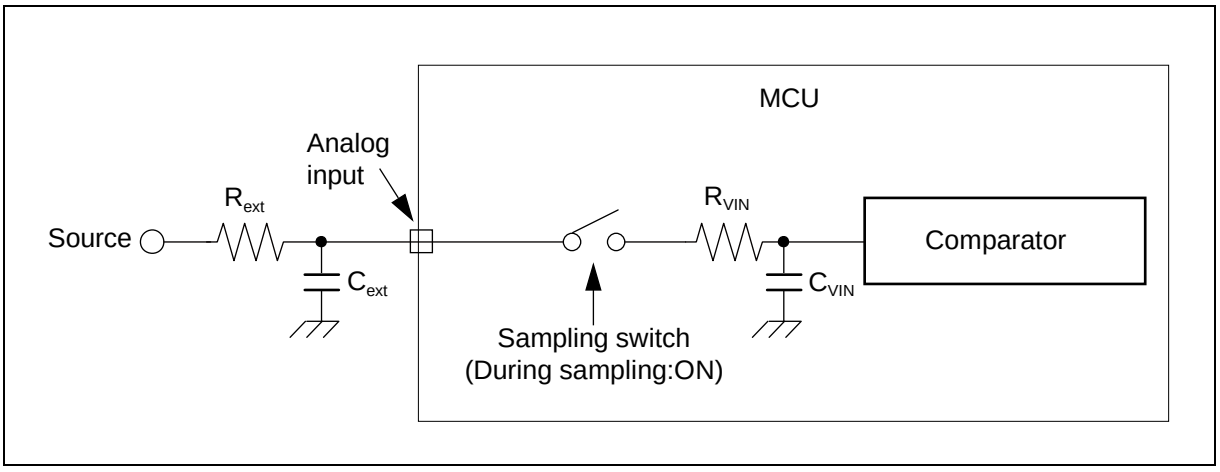
Parameter	Symbol	Pin name	Value			Unit
			Min	Typ	Max	
Power on rise time	t_R	Vcc	0.05	-	30	ms
Power off time	t_{OFF}	Vcc	1	-	-	ms



14.5.2 Accuracy and Setting of the A/D Converter Sampling Time

If the external impedance is too high or the sampling time too short, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting the A/D conversion precision.

To satisfy the A/D conversion precision, a sufficient sampling time must be selected. The required sampling time (Tsamp) depends on the external driving impedance R_{ext}, the board capacitance of the A/D converter input pin C_{ext} and the AV_{CC} voltage level. The following replacement model can be used for the calculation:



R_{ext}: External driving impedance

C_{ext}: Capacitance of PCB at A/D converter input

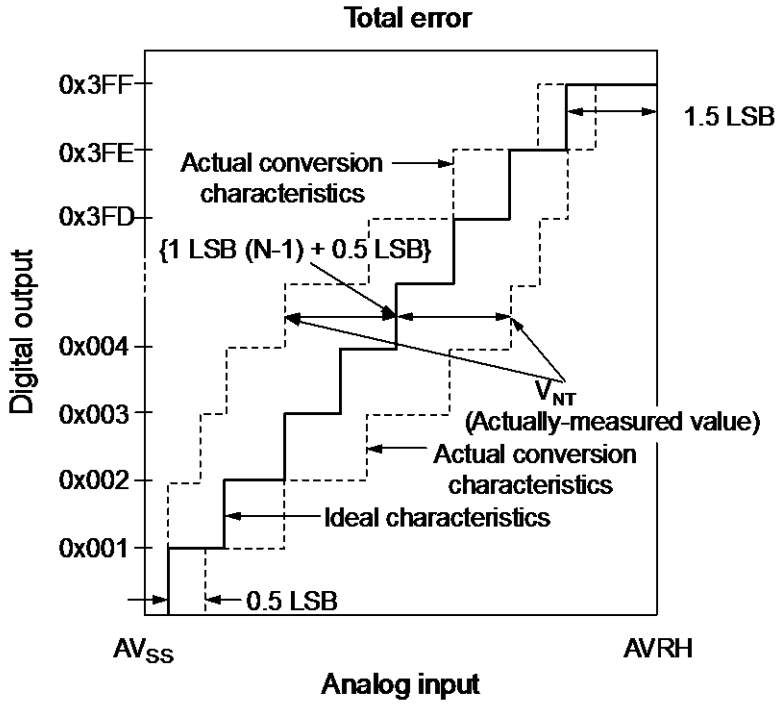
C_{VIN}: Analog input capacity (I/O, analog switch and ADC are contained)

R_{VIN}: Analog input impedance (I/O, analog switch and ADC are contained)

The following approximation formula for the replacement model above can be used:

$Tsamp = 7.62 \times (Rext \times Cext + (Rext + R_{VIN}) \times C_{VIN})$

- Do not select a sampling time below the absolute minimum permitted value.
  ($0.5\mu s$ for $4.5V \le AV_{CC} \le 5.5V$, $1.2\mu s$ for $2.7V \le AV_{CC} < 4.5V$)
- If the sampling time cannot be sufficient, connect a capacitor of about $0.1\mu F$ to the analog input pin.
- A big external driving impedance also adversely affects the A/D conversion precision due to the pin input leakage current IIL (static current before the sampling switch) or the analog input leakage current IAIN (total leakage current of pin input and comparator during sampling). The effect of the pin input leakage current IIL cannot be compensated by an external capacitor.
- The accuracy gets worse as $|AVRH - AV_{SS}|$ becomes smaller.



$$1LSB\ (Ideal\ value) = \frac{AVRH - AV_{SS}}{1024}\ [V]$$

$$Total\ error\ of\ digital\ output\ N = \frac{V_{NT} - \{1LSB \times (N - 1) + 0.5LSB\}}{1LSB}$$

N : A/D converter digital output value.
V_{NT} : Voltage at which the digital output changes from 0x(N + 1) to 0xN.
V_{OT} (Ideal value) = AV_{SS} + 0.5LSB[V]
V_{FST} (Ideal value) = AVRH - 1.5LSB[V]

14.7 Flash Memory Write/Erase Characteristics

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

Parameter		Conditions	Value			Unit	Remarks
			Min	Typ	Max		
Sector erase time	Large Sector	T_A ≤ + 105°C	-	1.6	7.5	s	Includes write time prior to internal erase.
	Small Sector	-	-	0.4	2.1	s	
	Security Sector	-	-	0.31	1.65	s	
Word (16-bit) write time	Large Sector	T_A ≤ + 105°C	-	25	400	µs	Not including system-level overhead time.
	Small Sector	-	-	25	400	µs	
Chip erase time		T_A ≤ + 105°C	-	5.11	25.05	s	Includes write time prior to internal erase.

Note:

While the Flash memory is written or erased, shutdown of the external power (V_{CC}) is prohibited. In the application system where the external power (V_{CC}) might be shut down while writing or erasing, be sure to turn the power off by using a low voltage detection function.

To put it concrete, change the external power in the range of change ration of power supply voltage (-0.004V/µs to +0.004V/µs) after the external power falls below the detection voltage (V_{DLX})[*1].

Write/Erase cycles and data hold time

Write/Erase cycles (cycle)	Data hold time (year)
1,000	20 [*2]
10,000	10 [*2]
100,000	5 [*2]

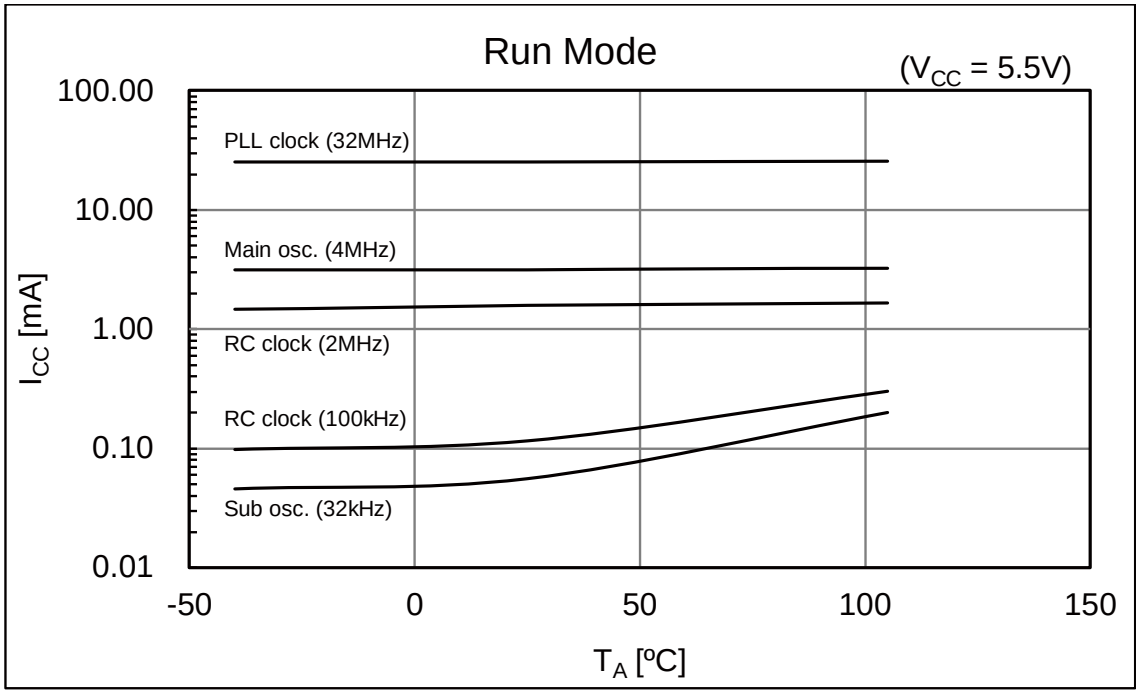
[*1]: See "Low Voltage Detection Function Characteristics".

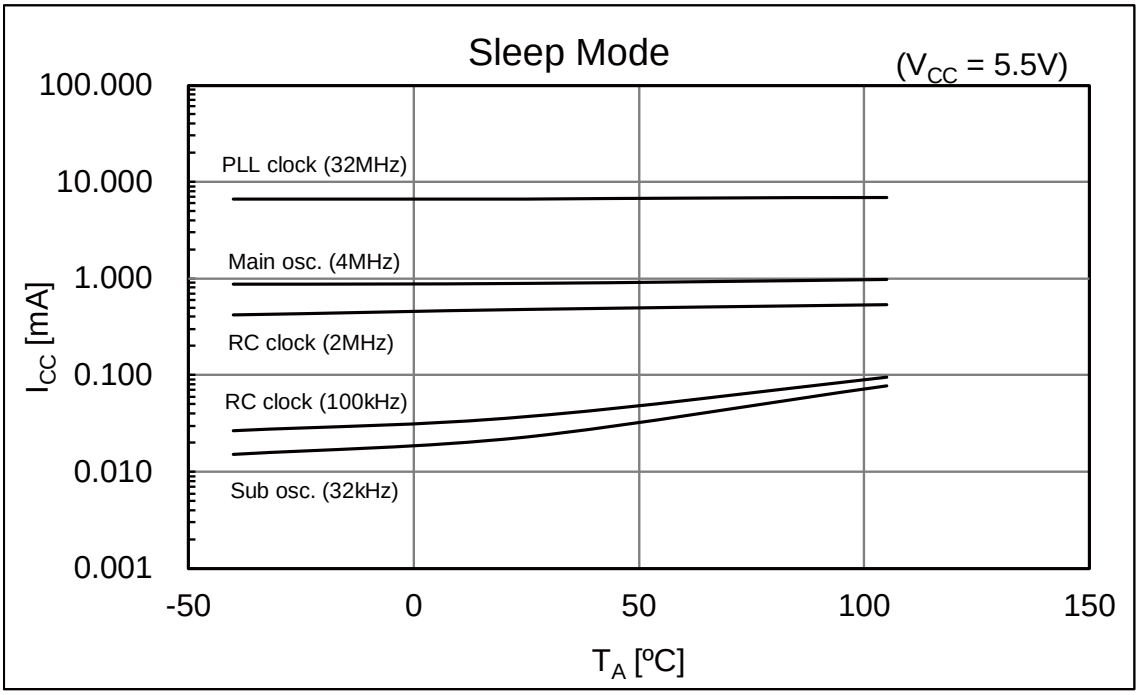
[*2]: This value comes from the technology qualification (using Arrhenius equation to translate high temperature measurements into normalized value at + 85°C).

15. Example Characteristics

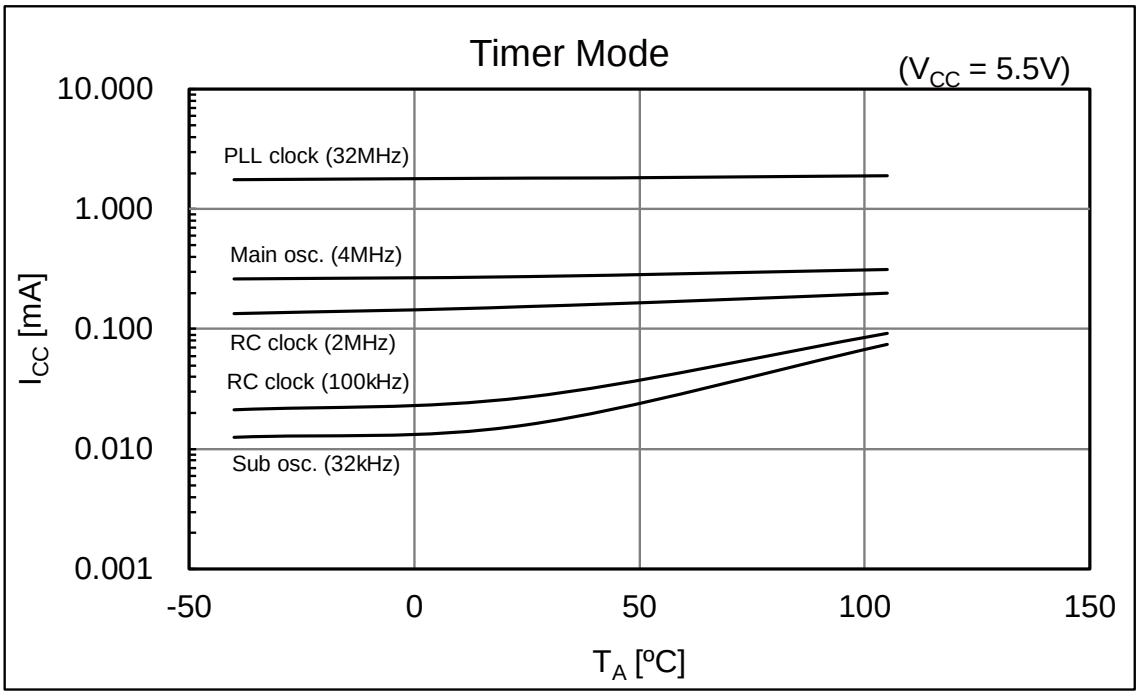
This characteristic is an actual value of the arbitrary sample. It is not the guaranteed value.

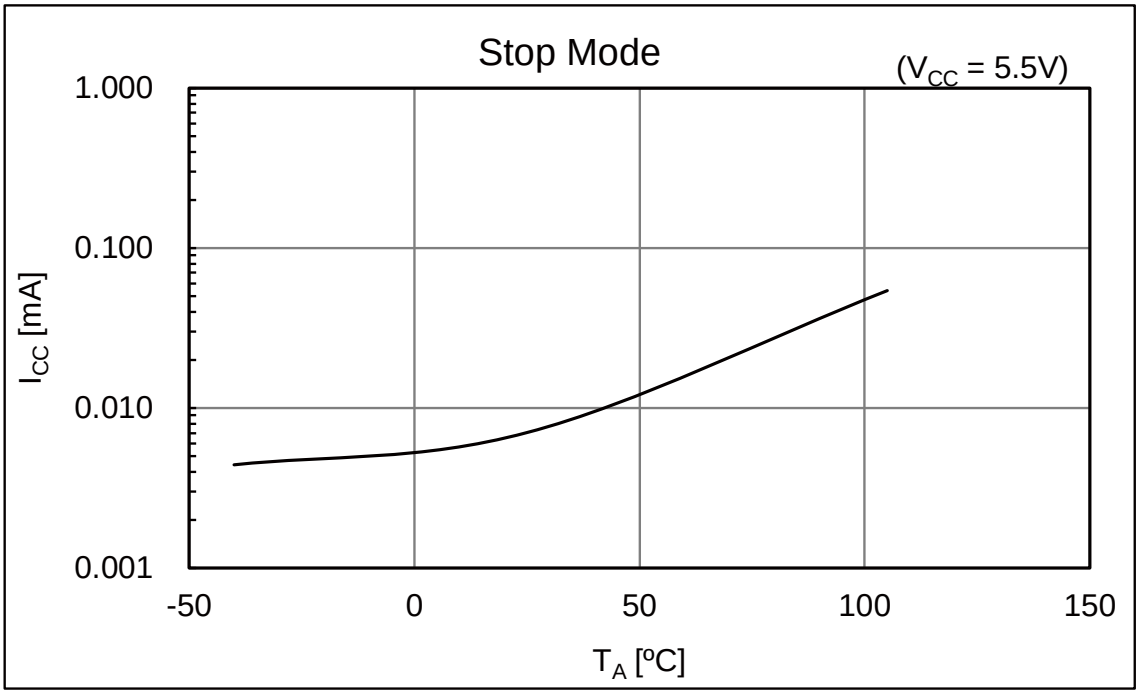
■MB96F625





■MB96F625


Timer Mode
(V_{CC} = 5.5V)
10.000
1.000
0.100
0.010
0.001
I_{CC} [mA]
PLL clock (32MHz)
Main osc. (4MHz)
RC clock (2MHz)
RC clock (100kHz)
Sub osc. (32kHz)
-50
0
50
100
150
T_A [ºC]


Stop Mode
(V_{CC} = 5.5V)
1.000
0.100
0.010
0.001
I_{CC} [mA]
-50
0
50
100
150
T_A [ºC]

Page	Section	Change Results
56	Electrical Characteristics 7. Flash Memory Write/Erase Characteristics	Changed the Note While the Flash memory is written or erased, shutdown of the external power (V_{CC}) is prohibited. In the application system where the external power (V_{CC}) might be shut down while writing, be sure to turn the power off by using an external voltage detector. → While the Flash memory is written or erased, shutdown of the external power (V_{CC}) is prohibited. In the application system where the external power (V_{CC}) might be shut down while writing or erasing, be sure to turn the power off by using a low voltage detection function.
60	Ordering Information	Deleted the Part number MCU with CAN controller MB96F622RBPMC-GTE2 MB96F622RBPMC1-GTE2 MB96F623RBPMC-GTE2 MB96F623RBPMC1-GTE2 MB96F625RBPMC-GTE2 MB96F625RBPMC1-GTE2 MCU without CAN controller MB96F622ABPMC-GTE2 MB96F622ABPMC1-GTE2 MB96F623ABPMC-GTE2 MB96F623ABPMC1-GTE2 MB96F625ABPMC-GTE2 MB96F625ABPMC1-GTE2
Revision 2.1		
-	-	Company name and layout design change

NOTE: Please see “Document History” about later revised information.

Sales, Solutions, and Legal Information

Worldwide Sales and Design Support

Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives, and distributors. To find the office closest to you, visit us at Cypress Locations.

Products

Automotive	cypress.com/go/automotive
Clocks & Buffers	cypress.com/go/clocks
Interface	cypress.com/go/interface
Lighting & Power Control	cypress.com/go/powerpsoc
Memory	cypress.com/go/memory
PSoC	cypress.com/go/psoc
Touch Sensing	cypress.com/go/touch
USB Controllers	cypress.com/go/USB
Wireless/RF	cypress.com/go/wireless
Spansion Products	cypress.com/spansionproducts

PSoC® Solutions

psoc.cypress.com/solutions

PSoC 1 | PSoC 3 | PSoC 4 | PSoC 5LP

Cypress Developer Community

Community | Forums | Blogs | Video | Training

Technical Support

cypress.com/go/support